



TAIYO YUDEN CO., LTD.

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Dear Taiyo Yuden customers,

January 3, 2007

Information about Lead-Free Taiyo Yuden Bluetooth Module

I would like to express my thanks for your loyal patronage.

Taiyo Yuden will start to comply with RoHS and elimination of regulated substances.

We will stop using lead products for our Bluetooth module. Please refer the below details for confirmation.

(1) Correspond Items

EYSF2CAXX, EYSF2CSXX, EYSF2CAXX-XX and the line items
EYSF2CMM, EYMF2CSMM, EYMF2CMM-XX and the line items

(2) Changes

We had used solder materials including lead. However we choose and start to use lead-free solder materials.

IC manufacturer used lead-materials for BGA bumps which are included in our modules. Now they switched over lead-free BGA bumps and we also start to make lead-free products by using lead-free materials (solder paste) instead of lead materials (solder paste). This makes our products compliant with RoHS. However lead as lead oxide is still included in components such as ceramics and etc.

(3) Reliability Verification

This change is applied only to BGA components and materials of solder paste as explained in (2). Therefore we perform usual mechanical evaluation on Thermal Cycle test and Drop test as our reliability verification.

From both evaluations we get equivalent/better results as/than existing products (lead-components) and see there is no problem in the lead -free products.

(4) Product handling

There is no change in conditions of the use of lead-free components from lead-components. Module external electrodes have been lead-free by Nickel/Gold plating surface finishing. Therefore there is no change in warnings and cautions for module mounting. Please refer existing "Handling Precaution" including reflow profile and handling conditions.

(5) Schedule

Please let us know if you have any other conditions or objections than mentioned in this document for using lead-free materials by the end of October, 2004.

If we do not hear from you, we will deem that the lead-free materials receive your approval.

Regarding traceability, we will inform you first lot number which complies with lead-free.
By the end of January, 2005, we will start using lead-free components for all of our products.
Please contact us if you wish to confirm lead-free schedule of particular item.

Please understand that we will stop shipment of existing products (lead components) by the end of March as part of the protection of the environment despite a request of continuous delivery.

(6) Others

There is no change in product ID of lead-free products from lead products.

There is no difference in application details for BT LOGO Qualification and Type Approvals due to change to lead-free materials. Therefore it is not necessary to re-acquire certifications or application for change.

We will appreciate your kind understandings and cooperation.

Taiyo Yuden Co., Ltd.
Module Product Unit
Wireless Engineering Div.

A handwritten signature in black ink, appearing to read "M. Takagi". The signature is written in a cursive, flowing style.